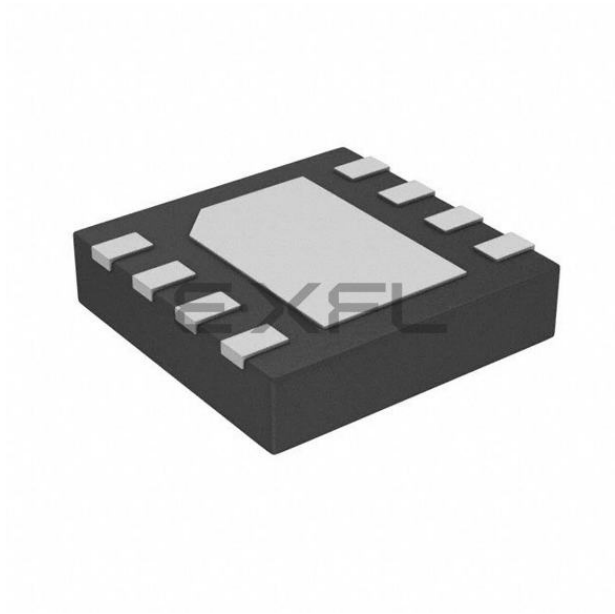

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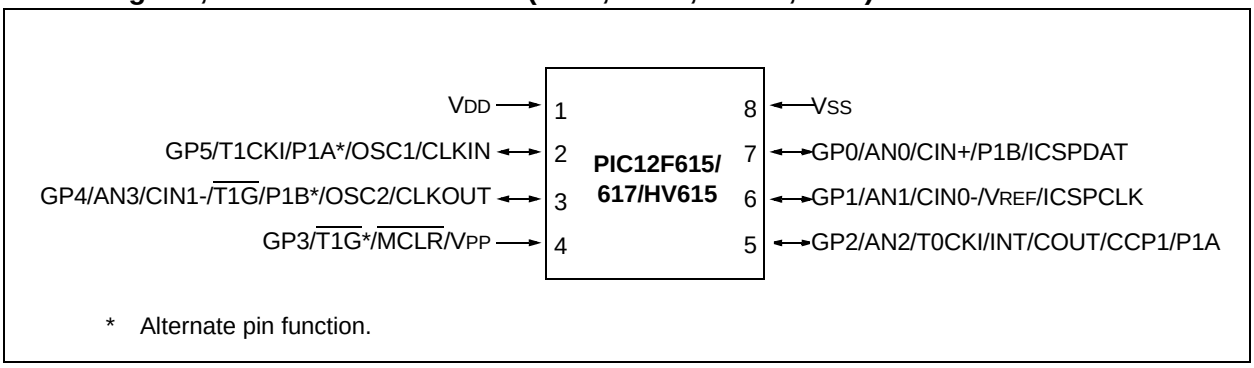
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12hv609-e-mf

8-Pin Diagram, PIC12F615/617/HV615 (PDIP, SOIC, MSOP, DFN)



* Alternate pin function.

TABLE 2: PIC12F615/617/HV615 PIN SUMMARY (PDIP, SOIC, MSOP, DFN)

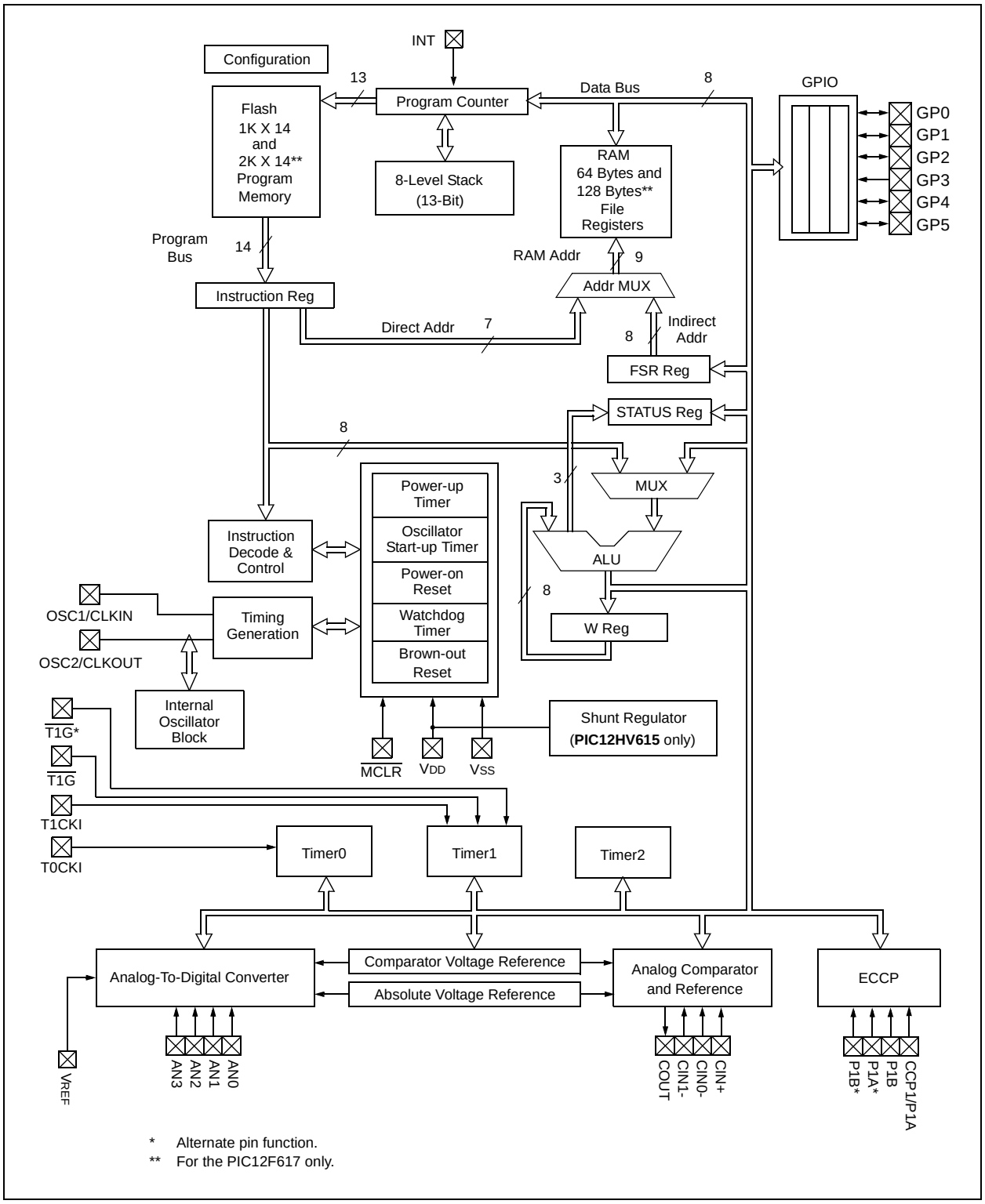
I/O	Pin	Analog	Comparators	Timer	CCP	Interrupts	Pull-ups	Basic
GP0	7	AN0	CIN+	—	P1B	IOC	Y	ICSPDAT
GP1	6	AN1	CIN0-	—	—	IOC	Y	ICSPCLK/VREF
GP2	5	AN2	COUT	T0CKI	CCP1/P1A	INT/IOC	Y	—
GP3(1)	4	—	—	T1G*	—	IOC	Y(2)	MCLR/VPP
GP4	3	AN3	CIN1-	T1G	P1B*	IOC	Y	OSC2/CLKOUT
GP5	2	—	—	T1CKI	P1A*	IOC	Y	OSC1/CLKIN
—	1	—	—	—	—	—	—	VDD
—	8	—	—	—	—	—	—	VSS

* Alternate pin function.

Note 1: Input only.

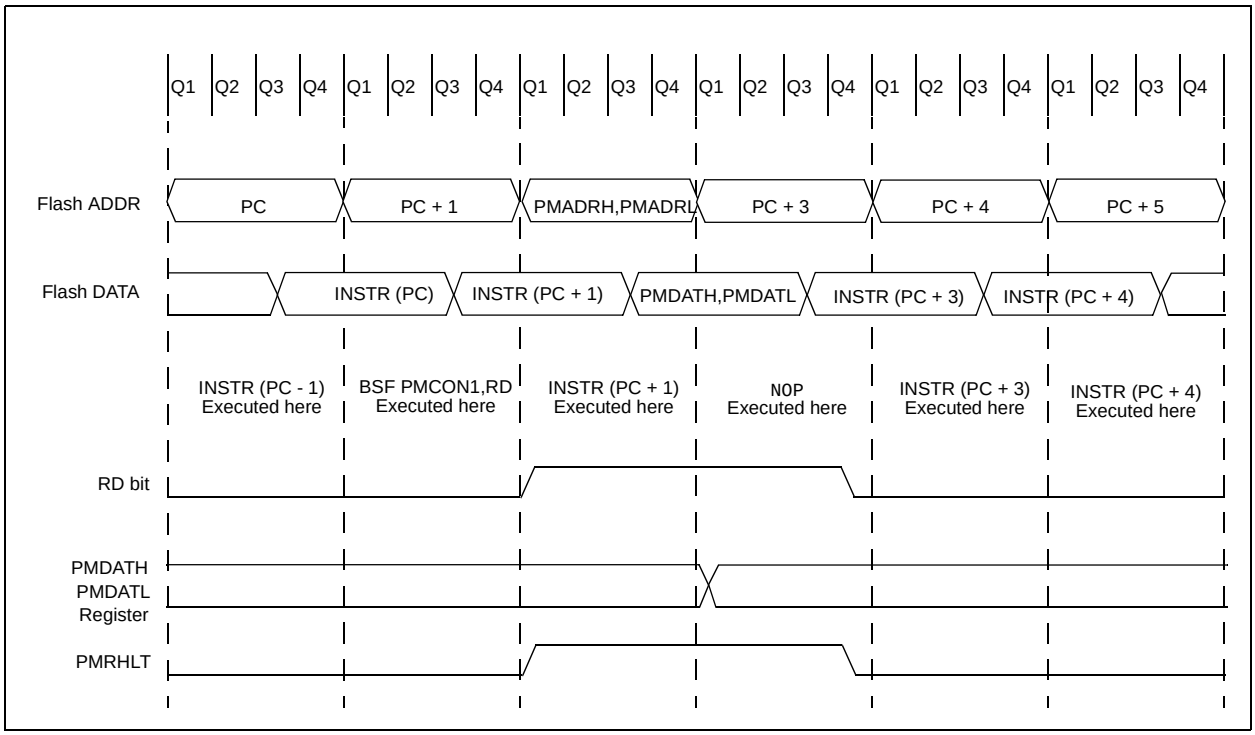
2: Only when pin is configured for external MCLR.

FIGURE 1-2: PIC12F615/617/HV615 BLOCK DIAGRAM



* Alternate pin function.
** For the PIC12F617 only.

FIGURE 3-1: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



4.3.3 LP, XT, HS MODES

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 4-3). The mode selects a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

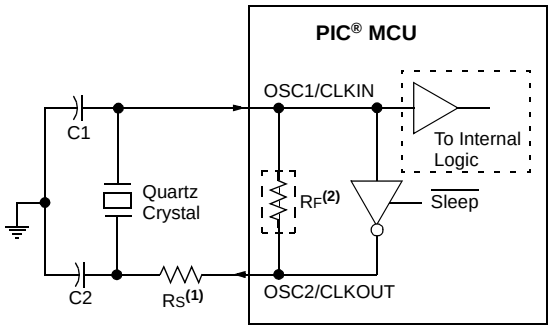
LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 4-3 and Figure 4-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

FIGURE 4-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

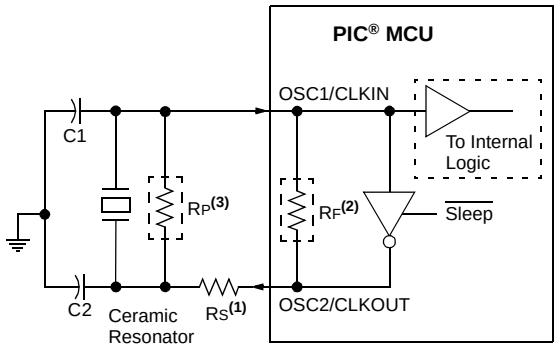
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 4-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

REGISTER 5-3: ANSEL: ANALOG SELECT REGISTER (PIC12F609/HV609)

U-0	U-0	U-0	U-0	R/W-1	U-0	R/W-1	R/W-1
—	—	—	—	ANS3	—	ANS1	ANS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **Unimplemented**: Read as '0'

bit 3 **ANS3**: Analog Select Between Analog or Digital Function on Pin GP4
1 = Analog input. Pin is assigned as analog input(1).
0 = Digital I/O. Pin is assigned to port or special function.

bit 2 **Unimplemented**: Read as '0'

bit 1 **ANS1:** Analog Select Between Analog or Digital Function on Pin GP1
1 = Analog input. Pin is assigned as analog input.(1)
0 = Digital I/O. Pin is assigned to port or special function.

bit 0 **ANS0:** Analog Select Between Analog or Digital Function on Pin GP0
0 = Digital I/O. Pin is assigned to port or special function.
1 = Analog input. Pin is assigned as analog input.(1)

Note 1: Setting a pin to an analog input automatically disables the digital input circuitry, weak pull-ups, and interrupt-on-change if available. The corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 5-4: ANSEL: ANALOG SELECT REGISTER (PIC12F615/617/HV615)

U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	ADCS2	ADCS1	ADCS0	ANS3	ANS2	ANS1	ANS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

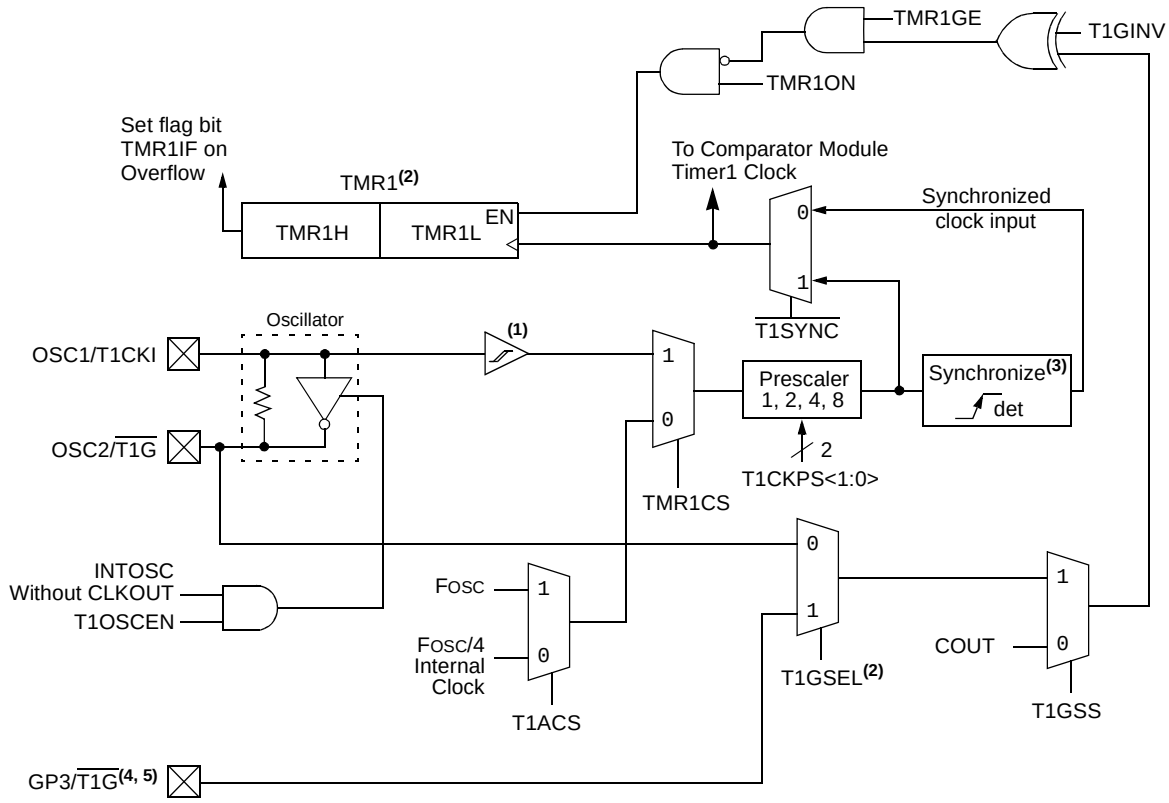
bit 7 **Unimplemented**: Read as '0'

bit 6-4 **ADCS<2:0>:** A/D Conversion Clock Select bits
000 = Fosc/2
001 = Fosc/8
010 = Fosc/32
x11 = FRC (clock derived from a dedicated internal oscillator = 500 kHz max)
100 = Fosc/4
101 = Fosc/16
110 = Fosc/64

bit 3-0 **ANS<3:0>**: Analog Select Between Analog or Digital Function on Pins GP4, GP2, GP1, GP0, respectively.
1 = Analog input. Pin is assigned as analog input(1).
0 = Digital I/O. Pin is assigned to port or special function.

Note 1: Setting a pin to an analog input automatically disables the digital input circuitry, weak pull-ups, and interrupt-on-change if available. The corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

FIGURE 7-1: TIMER1 BLOCK DIAGRAM



Note 1: ST Buffer is low power type when using LP oscillator, or high speed type when using T1CKI.
2: Timer1 register increments on rising edge.
3: Synchronize does not operate while in Sleep.
4: Alternate pin function.
5: PIC12F615/617/HV615 only.

11.0 ENHANCED CAPTURE/ COMPARE/PWM (WITH AUTO-SHUTDOWN AND DEAD BAND) MODULE (PIC12F615/617/ HV615 ONLY)

The Enhanced Capture/Compare/PWM module is a peripheral which allows the user to time and control different events. In Capture mode, the peripheral allows the timing of the duration of an event.The Compare mode allows the user to trigger an external event when a predetermined amount of time has expired. The PWM mode can generate a Pulse-Width Modulated signal of varying frequency and duty cycle.

Table 11-1 shows the timer resources required by the ECCP module.

TABLE 11-1: ECCP MODE – TIMER RESOURCES REQUIRED

ECCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

REGISTER 11-1: CCP1CON: ENHANCED CCP1 CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
P1M	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **P1M:** PWM Output Configuration bits
If CCP1M<3:2> = 00, 01, 10:
x = P1A assigned as Capture/Compare input; P1B assigned as port pins
If CCP1M<3:2> = 11:
0 = Single output; P1A modulated; P1B assigned as port pins
1 = Half-Bridge output; P1A, P1B modulated with dead-band control

bit 6 **Unimplemented:** Read as ‘0’

bit 5-4 **DC1B<1:0>:** PWM Duty Cycle Least Significant bits
Capture mode:
Unused.
Compare mode:
Unused.
PWM mode:
These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPR1L.

bit 3-0 **CCP1M<3:0>:** ECCP Mode Select bits
0000 =Capture/Compare/PWM off (resets ECCP module)
0001 =Unused (reserved)
0010 =Compare mode, toggle output on match (CCP1IF bit is set)
0011 =Unused (reserved)
0100 =Capture mode, every falling edge
0101 =Capture mode, every rising edge
0110 =Capture mode, every 4th rising edge
0111 =Capture mode, every 16th rising edge
1000 =Compare mode, set output on match (CCP1IF bit is set)
1001 =Compare mode, clear output on match (CCP1IF bit is set)
1010 =Compare mode, generate software interrupt on match (CCP1IF bit is set, CCP1 pin is unaffected)
1011 =Compare mode, trigger special event (CCP1IF bit is set; CCP1 resets TMR1 or TMR2 and starts an A/D conversion, if the ADC module is enabled)
1100 =PWM mode; P1A active-high; P1B active-high
1101 =PWM mode; P1A active-high; P1B active-low
1110 =PWM mode; P1A active-low; P1B active-high
1111 =PWM mode; P1A active-low; P1B active-low

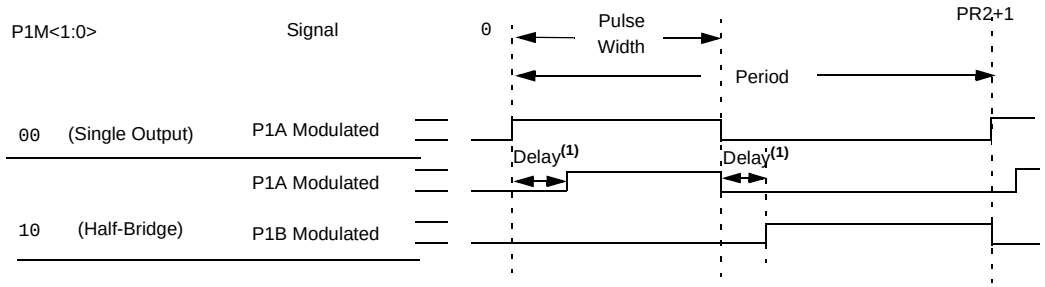
TABLE 11-3: SUMMARY OF REGISTERS ASSOCIATED WITH COMPARE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
CCP1CON	P1M	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	0-00 0000	0-00 0000
CCPR1L	Capture/Compare/PWM Register 1 Low Byte								xxxx xxxx	uuuu uuuu
CCPR1H	Capture/Compare/PWM Register 1 High Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	0000 0000
PIE1	—	ADIE(1)	CCP1IE(1)	—	CMIE	—	TMR2IE(1)	TMR1IE	-00- 0-00	-00- 0-00
PIR1	—	ADIF(1)	CCP1IF(1)	—	CMIF	—	TMR2IF(1)	TMR1IF	-00- 0-00	-00- 0-00
T1CON	T1GINV	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	0000 0000	uuuu uuuu
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR2	Timer2 Module Register								0000 0000	0000 0000
TRISIO	—	—	TRISIO5	TRISIO4	TRISIO3	TRISIO2	TRISIO1	TRISIO0	--11 1111	--11 1111

Legend: - = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Compare.

Note 1: For PIC12F615/617/HV615 only.

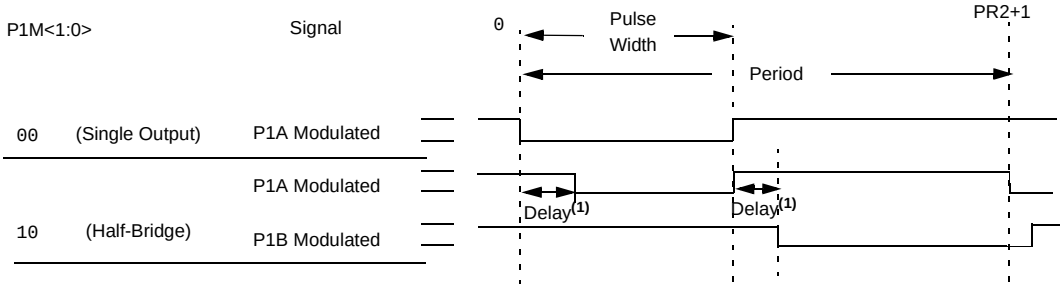
FIGURE 11-6: EXAMPLE PWM (ENHANCED MODE) OUTPUT RELATIONSHIPS (ACTIVE-HIGH STATE)



Relationships:
- Period = 4 * Tosc * (PR2 + 1) * (TMR2 Prescale Value)
- Pulse Width = Tosc * (CCPR1L<7:0>:CCP1CON<5:4>) * (TMR2 Prescale Value)
- Delay = 4 * Tosc * (PWM1CON<6:0>)

Note 1: Dead-band delay is programmed using the PWM1CON register (**Section 11.4.6 "Programmable Dead-Band Delay mode"**).

FIGURE 11-7: EXAMPLE ENHANCED PWM OUTPUT RELATIONSHIPS (ACTIVE-LOW STATE)



Relationships:
- Period = 4 * Tosc * (PR2 + 1) * (TMR2 Prescale Value)
- Pulse Width = Tosc * (CCPR1L<7:0>:CCP1CON<5:4>) * (TMR2 Prescale Value)
- Delay = 4 * Tosc * (PWM1CON<6:0>)

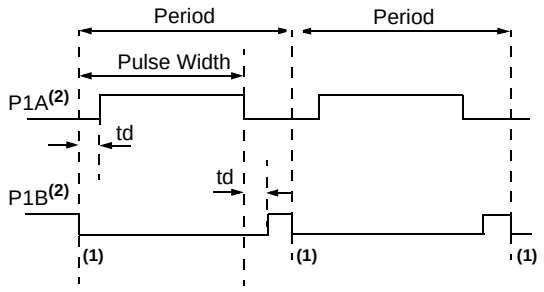
Note 1: Dead-band delay is programmed using the PWM1CON register (**Section 11.4.6 "Programmable Dead-Band Delay mode"**).

11.4.6 PROGRAMMABLE DEAD-BAND DELAY MODE

In Half-Bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shoot-through current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

In Half-Bridge mode, a digitally programmable dead-band delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 11-13 for illustration. The lower seven bits of the associated PWMxCON register (Register 11-3) sets the delay period in terms of microcontroller instruction cycles (TCY or 4 TOSC).

FIGURE 11-13: EXAMPLE OF HALF-BRIDGE PWM OUTPUT

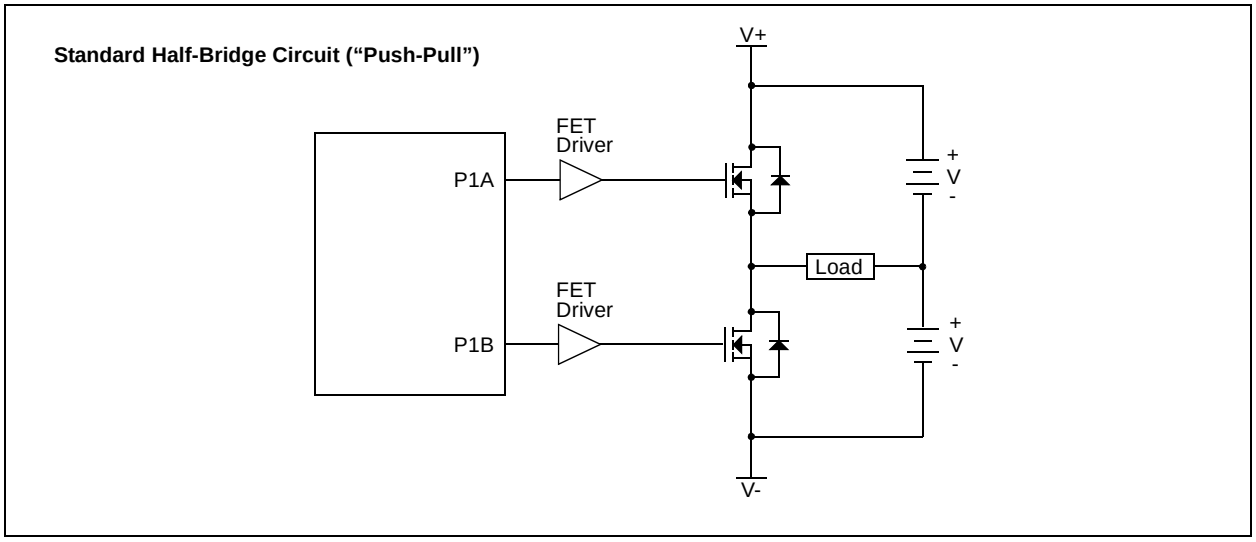


td = Dead-Band Delay

Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signals are shown as active-high.

FIGURE 11-14: EXAMPLE OF HALF-BRIDGE APPLICATIONS



NOTES:

TABLE 12-4: INITIALIZATION CONDITION FOR REGISTERS (PIC12F609/HV609)

Register	Address	Power-on Reset	$\overline{\text{MCLR}}$ Reset WDT Reset Brown-out Reset(1)	Wake-up from Sleep through Interrupt Wake-up from Sleep through WDT Time-out
W	—	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h/80h	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h/82h	0000 0000	0000 0000	PC + 1(3)
STATUS	03h/83h	0001 1xxx	000q quuu(4)	uuuq quuu(4)
FSR	04h/84h	xxxx xxxx	uuuu uuuu	uuuu uuuu
GPIO	05h	--x0 x000	--u0 u000	--uu uuuu
PCLATH	0Ah/8Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh/8Bh	0000 0000	0000 0000	uuuu uuuu(2)
PIR1	0Ch	----- 0--0	---- 0--0	---- u--u(2)
TMR1L	0Eh	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	0Fh	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	10h	0000 0000	uuuu uuuu	-uuu uuuu
VRCON	19h	0-00 0000	0-00 0000	u-uu uuuu
CMCON0	1Ah	0000 -0-0	0000 -0-0	uuuu -u-u
CMCON1	1Ch	---0 0-10	---0 0-10	---u u-qu
OPTION_REG	81h	1111 1111	1111 1111	uuuu uuuu
TRISIO	85h	--11 1111	--11 1111	--uu uuuu
PIE1	8Ch	----- 0--0	---- 0--0	---- u--u
PCON	8Eh	---- --0x	---- --uu(1, 5)	---- --uu
OSCTUNE	90h	---0 0000	---u uuuu	---u uuuu
WPU	95h	--11 -111	--11 -111	--uu -uuu
IOC	96h	--00 0000	--00 0000	--uu uuuu
ANSEL	9Fh	---- 1-11	---- 1-11	---- q-qq

Legend: u = unchanged, x = unknown, – = unimplemented bit, reads as '0', q = value depends on condition.

Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON and/or PIR1 will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 12-6 for Reset value for specific condition.

5: If Reset was due to brown-out, then bit 0 = 0. All other Resets will cause bit 0 = u.

BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	$0 \le f \le 127$ $0 \le b < 7$
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.

CALL	Call Subroutine
Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(\bar{f}) \rightarrow$ (destination)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

DECF	Decrement f
Syntax:	[*label*] DECF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

16.1 DC Characteristics: PIC12F609/615/617/12HV609/615-I (Industrial) PIC12F609/615/617/12HV609/615-E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC12F609/615/617	2.0	—	5.5	V	FOSC < = 4 MHz
D001		PIC12HV609/615	2.0	—	—(2)	V	FOSC < = 4 MHz
D001B		PIC12F609/615/617	2.0	—	5.5	V	FOSC < = 8 MHz
D001B		PIC12HV609/615	2.0	—	—(2)	V	FOSC < = 8 MHz
D001C		PIC12F609/615/617	3.0	—	5.5	V	FOSC < = 10 MHz
D001C		PIC12HV609/615	3.0	—	—(2)	V	FOSC < = 10 MHz
D001D		PIC12F609/615/617	4.5	—	5.5	V	FOSC < = 20 MHz
D001D		PIC12HV609/615	4.5	—	—(2)	V	FOSC < = 20 MHz
D002*	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See **Section 12.3.1 "Power-on Reset (POR)"** for details.
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 12.3.1 "Power-on Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: User defined. Voltage across the shunt regulator should not exceed 5V.

16.8 DC Characteristics: PIC12F609/615/617/12HV609/615-I (Industrial) PIC12F609/615/617/12HV609/615-E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O port:					
D030		with TTL buffer	Vss	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D030A			Vss	—	0.15 VDD	V	2.0V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger buffer	Vss	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
D032		$\overline{MCLR}$, OSC1 (RC mode)	Vss	—	0.2 VDD	V	**(NOTE 1)**
D033		OSC1 (XT and LP modes)	Vss	—	0.3	V	
D033A		OSC1 (HS mode)	Vss	—	0.3 VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	VDD	V	2.0V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8 VDD	—	VDD	V	2.0V ≤ VDD ≤ 5.5V
D042		$\overline{MCLR}$	0.8 VDD	—	VDD	V	
D043		OSC1 (XT and LP modes)	1.6	—	VDD	V	
D043A		OSC1 (HS mode)	0.7 VDD	—	VDD	V	
D043B		OSC1 (RC mode)	0.9 VDD	—	VDD	V	**(NOTE 1)**
	IIL	**Input Leakage Current(2,3)**					
D060		I/O ports	—	± 0.1	± 1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
D061		GP3/$\overline{MCLR}$(3,4)	—	± 0.7	± 5	µA	VSS ≤ VPIN ≤ VDD
D063		OSC1	—	± 0.1	± 5	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP oscillator configuration
D070*	IPUR	**GPIO Weak Pull-up Current(5)**	50	250	400	µA	VDD = 5.0V, VPIN = VSS
	VOL	**Output Low Voltage**	—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
	VOH	**Output High Voltage**	VDD – 0.7	—	—	V	IOH = -2.5mA, VDD = 4.5V, -40°C to +125°C
D090		I/O ports(2)	VDD – 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: Negative current is defined as current sourced by the pin.

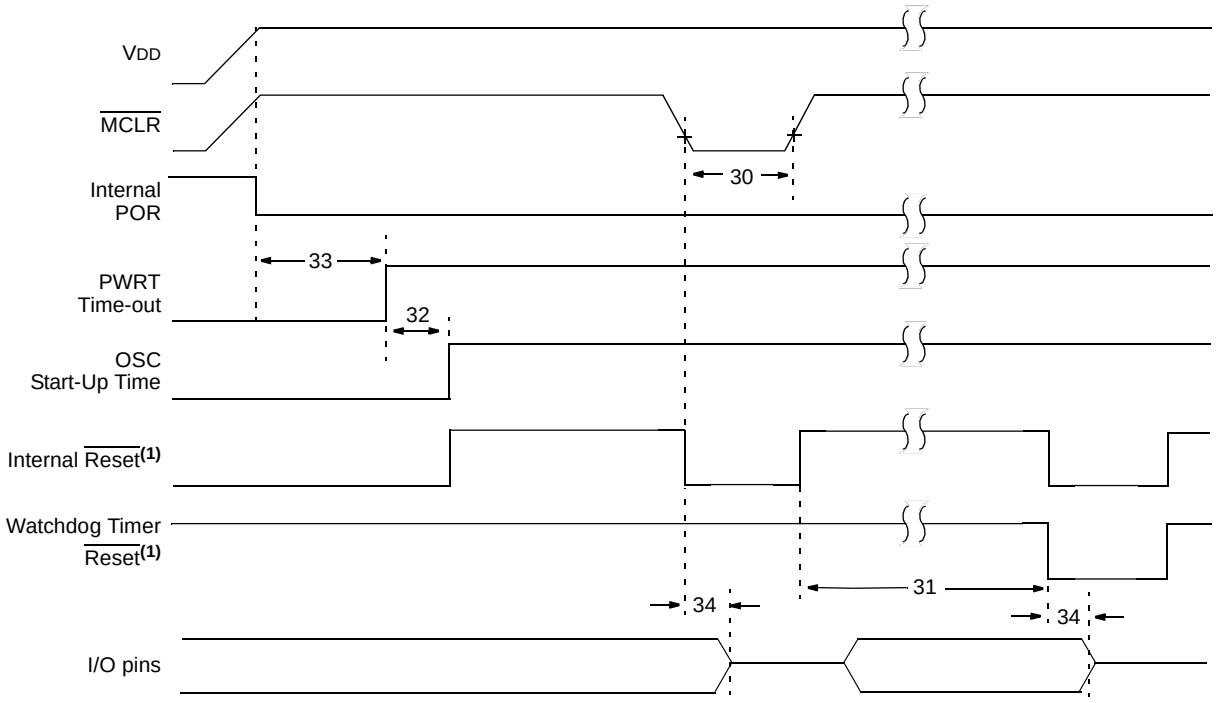
3: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

4: This specification applies to GP3/$\overline{MCLR}$ configured as GP3 with the internal weak pull-up disabled.

5: This specification applies to all weak pull-up pins, including the weak pull-up found on GP3/$\overline{MCLR}$. When GP3/$\overline{MCLR}$ is configured as $\overline{MCLR}$ reset pin, the weak pull-up is always enabled.

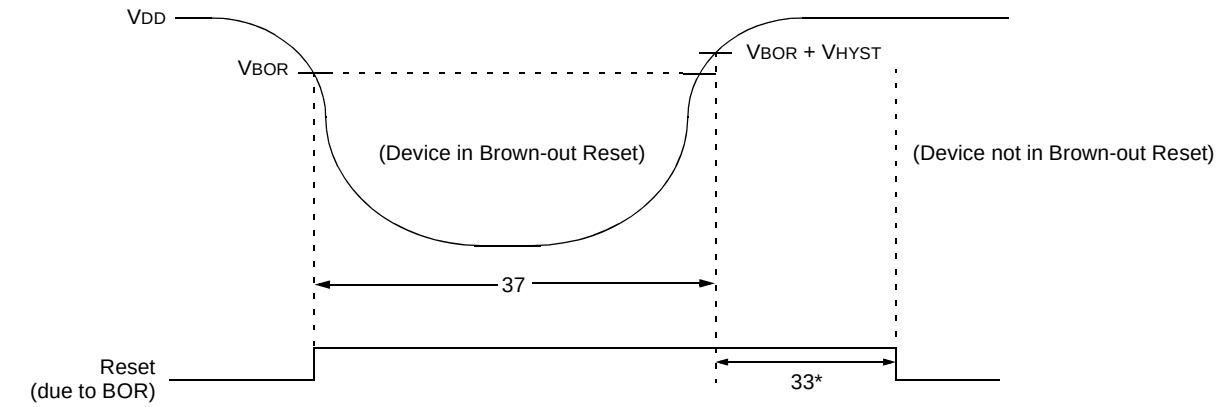
6: Applies to PIC12F617 only.

FIGURE 16-6: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note 1: Asserted low.

FIGURE 16-7: BROWN-OUT RESET TIMING AND CHARACTERISTICS



* 64 ms delay only if PWRTE bit in the Configuration Word register is programmed to '0'.

TABLE 16-11: PIC12F615/617/HV615 A/D CONVERTER (ADC) CHARACTERISTICS:

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10 bits	bit	
AD02	EIL	Integral Error	—	—	±1	LSb	VREF = 5.12V(5)
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes to 10 bits VREF = 5.12V(5)
AD04	EOFF	Offset Error	—	+1.5	+2.0	LSb	VREF = 5.12V(5)
AD07	EGN	Gain Error	—	—	±1	LSb	VREF = 5.12V(5)
AD06 AD06A	VREF	Reference Voltage(3)	2.2 2.5	—	— VDD	V	 Absolute minimum to ensure 1 LSb accuracy
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	
AD09*	IREF	VREF Input Current(3)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN.
			—	—	50	μA	During A/D conversion cycle.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

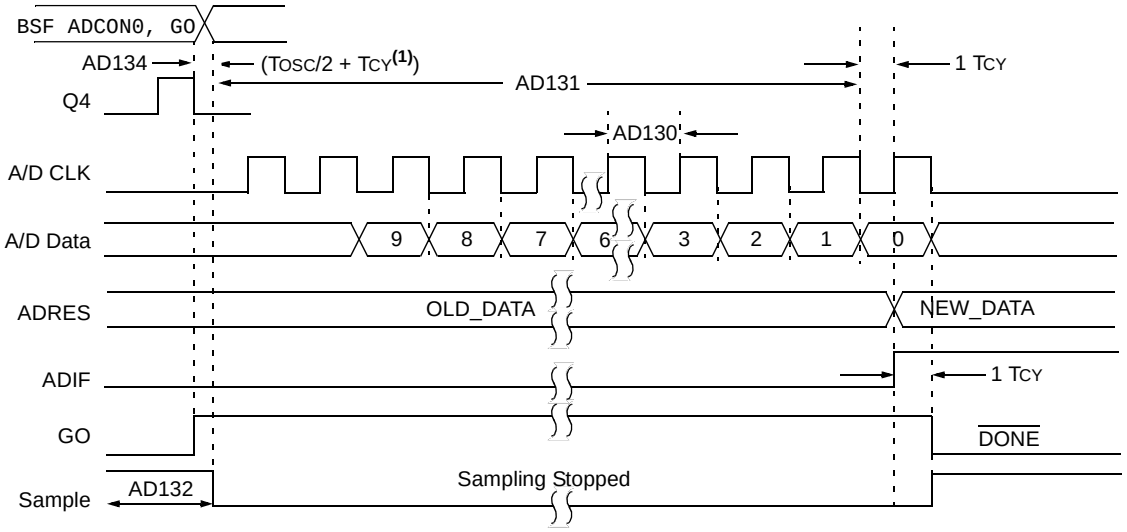
2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF or VDD pin, whichever is selected as reference input.

4: When ADC is off, it will not consume any current other than leakage current. The power-down current specification includes any such leakage from the ADC module.

5: VREF = 5V for PIC12HV615.

FIGURE 16-11: PIC12F615/617/HV615 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 17-45: TYPICAL HFINTOSC FREQUENCY CHANGE vs. VDD (125°C)

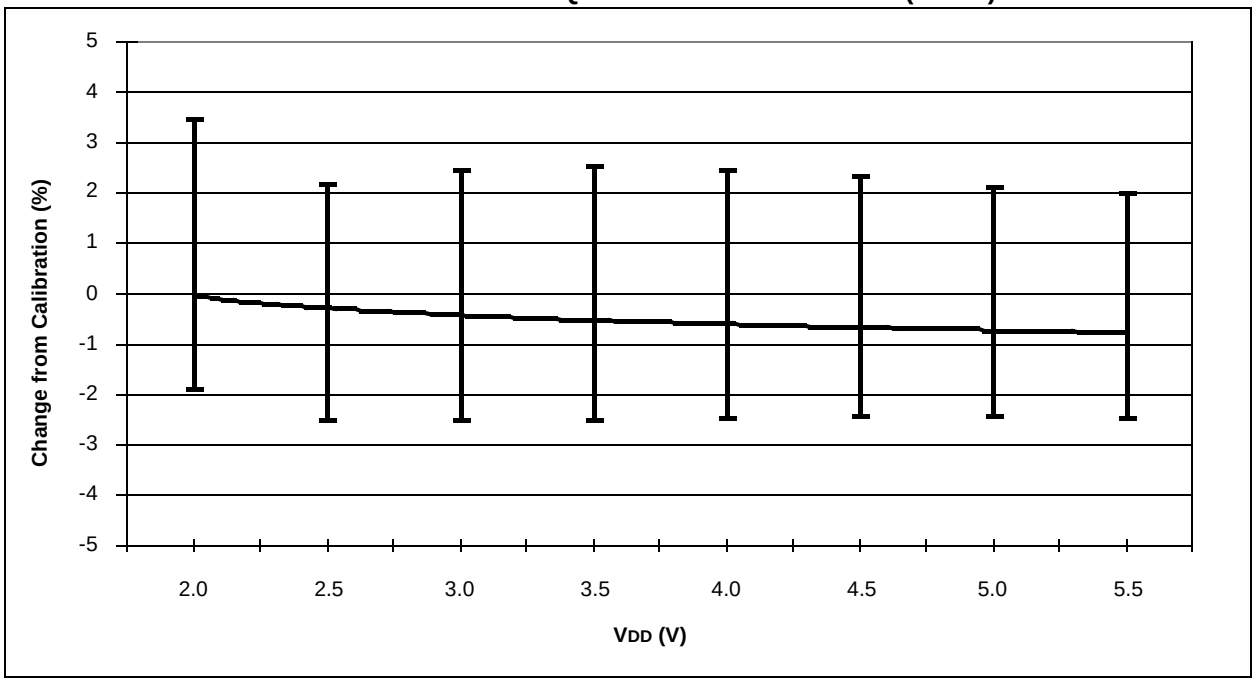


FIGURE 17-46: TYPICAL HFINTOSC FREQUENCY CHANGE vs. VDD (-40°C)